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**INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

JB/T 10845-2008

General process specification for lead-free reflow soldering

无铅再流焊接通用工艺规范

(English Translation)

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Table of Contents

2 Normative references

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JB/T 10845-2008 cites the following standards, which apply in full or in part through the references made to them in its clauses.

SJ/T 11216-1999